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# PHOTOCOUPLER PS2501A-1,PS2501AL-1

### HIGH ISOLATION VOLTAGE SINGLE TRANSISTOR TYPE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

### **DESCRIPTION**

The PS2501A-1 and PS2501AL-1 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor to realize an excellent cost performance.

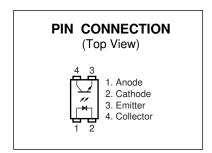
The PS2501A-1 is in a plastic DIP (Dual In-line Package) and the PS2501AL-1 is lead bending type (Gull-wing) for surface mount.

### **FEATURES**

- High isolation voltage (BV = 5 000 Vr.m.s.)
- Ordering number of taping product: PS2501AL-1-F3: 2 000 pcs/reel
  - · Pb-Free product
  - · Safety standards
    - UL approved: No. E72422

### **APPLICATIONS**

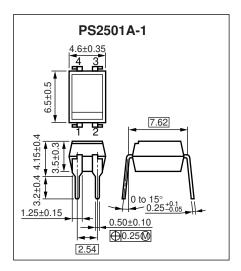
- · Power supply
- · Telephone/FAX.
- FA/OA equipment
- · Programmable logic controller



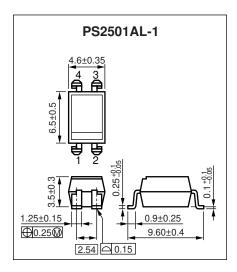
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### PACKAGE DIMENSIONS (UNIT: mm)

### **DIP Type**



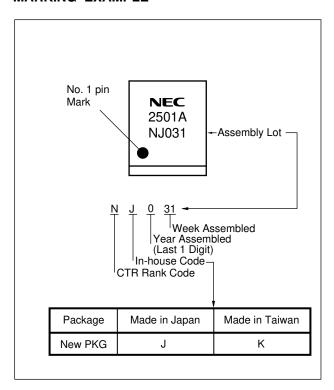
### **Lead Bending Type**



### \* PHOTOCOUPLER CONSTRUCTION

| Parameter               | Unit (MIN.) |  |  |
|-------------------------|-------------|--|--|
| Air Distance            | 7 mm        |  |  |
| Outer Creepage Distance | 7 mm        |  |  |
| Inner Creepage Distance | 3.5 mm      |  |  |
| Isolation Distance      | 0.3 mm      |  |  |

### **★ MARKING EXAMPLE**



### **\* ORDERING INFORMATION**

| Part Number   | Order Number    | Solder Plating<br>Specification | Packing Style                | Safety Standard<br>Approval | Application Part Number *1 |
|---------------|-----------------|---------------------------------|------------------------------|-----------------------------|----------------------------|
| PS2501A-1     | PS2501A-1-A     | Pb-Free                         | Magazine case 100 pcs        | Standard products           | PS2501A-1                  |
| PS2501AL-1    | PS2501AL-1-A    |                                 |                              | (UL Approved)               |                            |
| PS2501AL-1-F3 | PS2501AL-1-F3-A |                                 | Embossed Tape 2 000 pcs/reel |                             |                            |

<sup>\*1</sup> For the application of the Safety Standard, following part number should be used.

### ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

| Parameter                     |                              | Symbol           | Ratings     | Unit    |
|-------------------------------|------------------------------|------------------|-------------|---------|
| Diode                         | Reverse Voltage              | VR               | 6           | V       |
|                               | Forward Current (DC)         | lF               | 30          | mA/ch   |
|                               | Power Dissipation Derating   | ⊿Po/°C           | 1.5         | mW/°C   |
|                               | Power Dissipation            | PD               | 150         | mW      |
|                               | Peak Forward Current*1       | IFP              | 0.5         | A/ch    |
| Transistor                    | Collector to Emitter Voltage | Vceo             | 70          | V       |
|                               | Emitter to Collector Voltage | VECO             | 5           | V       |
|                               | Collector Current            | lc               | 30          | mA      |
|                               | Power Dissipation Delay      | ⊿Pc/°C           | 1.5         | mW/°C   |
|                               | Power Dissipation            | Pc               | 150         | mW      |
| Isolation Voltage*2           |                              | BV               | 5 000       | Vr.m.s. |
| Operating Ambient Temperature |                              | Та               | -55 to +100 | °C      |
| Storage Temperature           |                              | T <sub>stg</sub> | -55 to +150 | °C      |

<sup>\*1</sup> PW = 100  $\mu$ s, Duty Cycle = 1%

<sup>\*2</sup> AC voltage for 1 minute at  $T_A = 25$ °C, RH = 60% between input and output.

<sup>1-2</sup> shorted together, 3-4 shorted together.

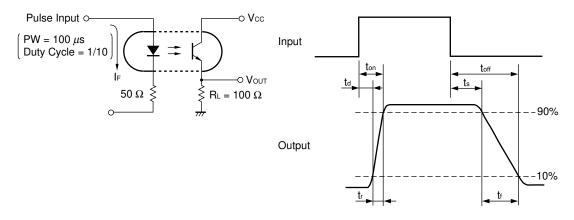
### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

|            | Parameter                            | Symbol           | Conditions   | MIN.             | TYP. | MAX. | Unit |
|------------|--------------------------------------|------------------|--|------------------|------|------|------|
| Diode      | Forward Voltage                      | VF               | IF = 10 mA   |                  | 1.2  | 1.4  | V    |
|            | Reverse Current                      | lR               | V <sub>R</sub> = 5 V                               |                  |      | 5    | μА   |
|            | Terminal Capacitance                 | Ct               | V = 0 V, f = 1.0 MHz                               |                  | 10   |      | pF   |
| Transistor | Collector to Emitter Dark<br>Current | Iceo             | VcE = 70 V, IF = 0 mA                              |                  |      | 100  | nA   |
| Coupled    | Current Transfer Ratio               | CTR              | $I_F = 5 \text{ mA}, \text{ V}_{CE} = 5 \text{ V}$ | 50               |      | 400  | %    |
|            | Collector Saturation<br>Voltage      | VCE (sat)        | IF = 10 mA, Ic = 2 mA                              |                  | 0.13 | 0.3  | V    |
|            | Isolation Resistance                 | R <sub>I-O</sub> | Vi-o = 1.0 kVdc                                    | 10 <sup>11</sup> |      |      | Ω    |
|            | Isolation Capacitance                | C <sub>I-O</sub> | V = 0 V, f = 1.0 MHz                               |                  | 0.4  |      | pF   |
|            | Rise Time*2                          | <b>t</b> r       | Vcc = 10 V, lc = 2 mA, RL = 100 $\Omega$           |                  | 3    |      | μS   |
|            | Fall Time*2                          | <b>t</b> f       |  |                  | 5    |      |      |

### ★ \*1 CTR rank

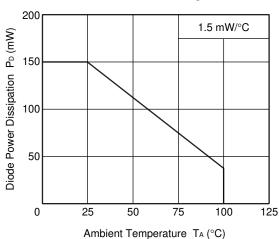
N : 50 to 400 (%) H : 80 to 160 (%) W : 130 to 260 (%) Q : 100 to 200 (%) L : 200 to 400 (%)

### \*2 Test circuit for switching time

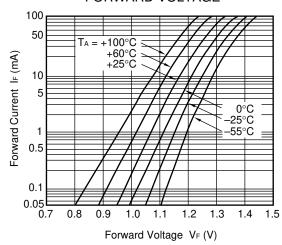


### TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

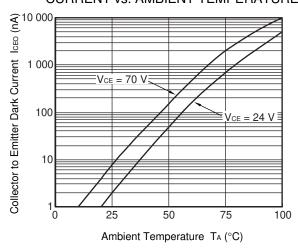




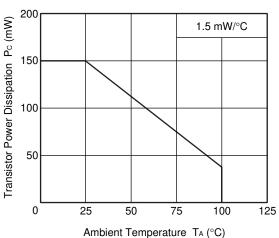
### FORWARD CURRENT vs. FORWARD VOLTAGE



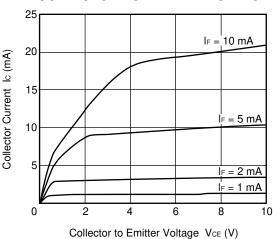
### COLLECTOR TO EMITTER DARK **CURRENT vs. AMBIENT TEMPERATURE**



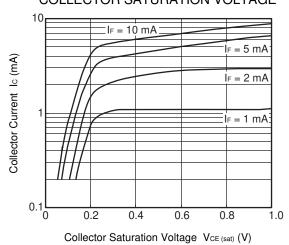
### TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



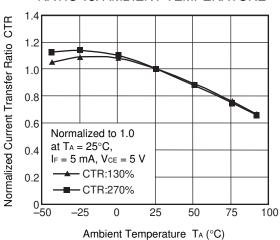
### COLLECTOR CURRENT vs. **COLLECTOR TO EMITTER VOLTAGE**



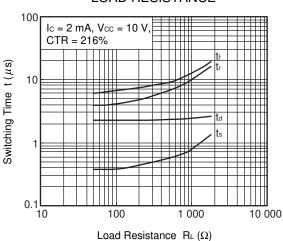
### COLLECTOR CURRENT vs. **COLLECTOR SATURATION VOLTAGE**



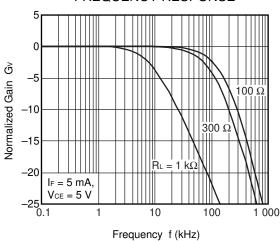
## NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



### SWITCHING TIME vs. LOAD RESISTANCE

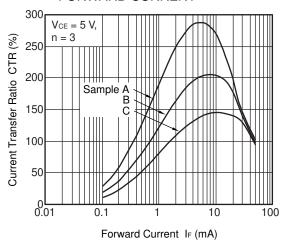


### FREQUENCY RESPONSE

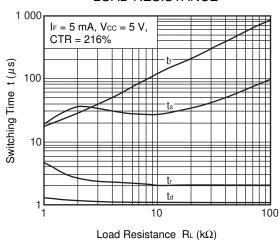


### **Remark** The graphs indicate nominal characteristics.

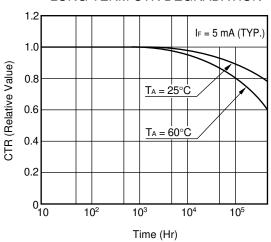
### CURRENT TRANSFER RATIO vs. FORWARD CURRENT



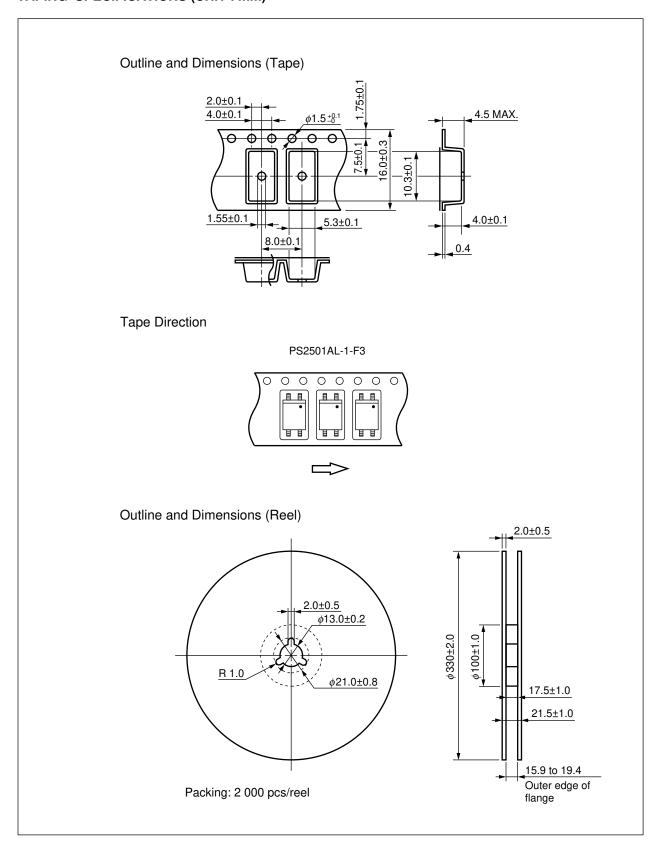
### SWITCHING TIME vs. LOAD RESISTANCE



### LONG TERM CTR DEGRADATION



### \* TAPING SPECIFICATIONS (UNIT : mm)



### NOTES ON HANDLING

### 1. Recommended soldering conditions

### (1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

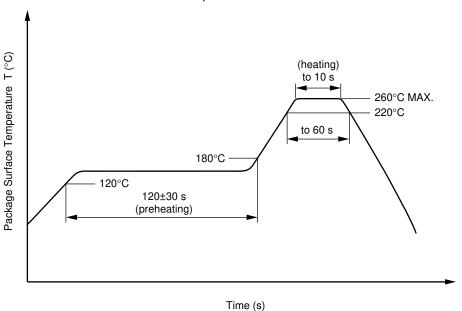
Time of peak reflow temperature
 Time of temperature higher than 220°C
 50 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

### Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times
 One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

### (3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

### (4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

### 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below IF = 1 mA

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

### **USAGE CAUTIONS**

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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### Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.